

FEATURES

- ❑ Pipeline Registers —
 - Dual 7-Deep (L29C524) or
 - Dual 8-Deep (L29C525)
- ❑ Configurable to Single 14-Deep and Single 16-Deep
- ❑ Low Power CMOS Technology
- ❑ Replaces AMD Am29524 and Am29525
- ❑ Load, Shift, and Hold Instructions
- ❑ Separate Data In and Data Out Pins
- ❑ Three-State Outputs
- ❑ DESC SMD No. 5962-91696
- ❑ Available 100% Screened to MIL-STD-883, Class B
- ❑ Package Styles Available:
 - 28-pin Plastic DIP
 - 28-pin Ceramic DIP
 - 28-pin Sidebraze, Hermetic DIP
 - 28-pin Ceramic Flatpack
 - 28-pin Plastic LCC, J-Lead

DESCRIPTION

The L29C524 and L29C525 are high-speed, low power CMOS pipeline registers. They are pin-for-pin compatible with the AMD Am29524 and Am29525. The products can be configured as two independent 7-level (or 8-level) pipelines or as single 14-level (or 16-level) pipeline. The configuration implemented is determined by the instruction code (I1-0) as shown in Table 2.

The I1-0 instruction code controls the internal routing of data and loading of each register. For instruction I1-0 = 00 (Push A and B), data applied at the D7-0 inputs is latched into register A0 on the rising edge of CLK. The contents of A0 simultaneously move to register A1, A1 moves to A2, and so on. The contents of the last register on the A side (A6 for the L29C524, A7 for the L29C525) are wrapped back to register B0. The registers on the B side are similarly shifted, with the contents of the last register on the B side (B6 for the L29C524, B7 for the L29C525) lost.

Instruction I1-0 = 01 (Push B) acts similarly to the Push A and B instruction, except that only the B side registers are shifted. The input data is applied to register B0, and the contents of the last register on the B side (B6 for the L29C524, B7 for the L29C525) are lost. The contents of the A side registers are unaffected. Instruction I1-0 = 10 (Push A) is identical to the Push B instruction, except that the A side registers are shifted and the B side registers are unaffected.

Instruction I1-0 = 11 (Hold) causes no internal data movement. It is equivalent to preventing the application of a clock edge to any internal register.

The contents of any of the registers is selectable at the output through the use of the S3-0 control inputs. On the L29C524, the input pins D7-0 may also be selected to drive the output, and all output pins may be forced to zero. The independence of the I and S control lines allows simultaneous reading and writing. Encoding for the S3-0 controls is given in Table 3.

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L29C524/525 BLOCK DIAGRAM

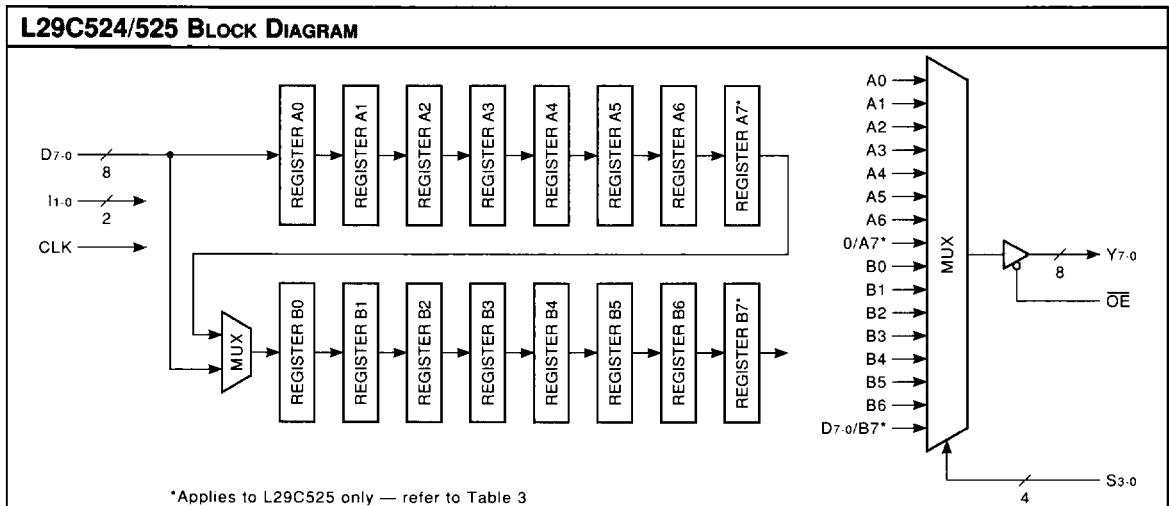
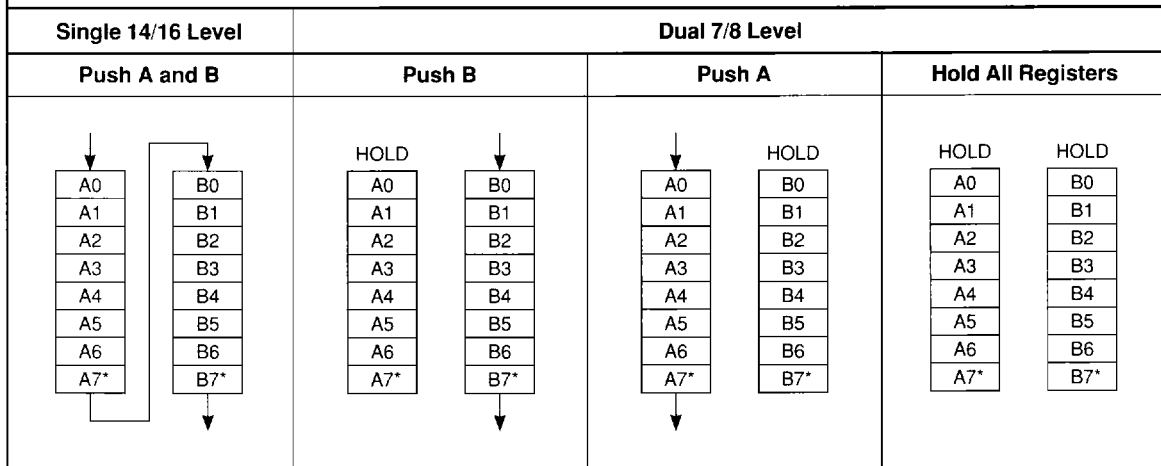


TABLE 1. REGISTER LOAD OPERATIONS


*Applies to L29C525 only

TABLE 2. INSTRUCTION SET

Mnemonics	Inputs		Description
	I ₁	I ₀	
Shift	0	0	Push A and B
LDB	0	1	Push B
LDA	1	0	Push A
HLD	1	1	Hold All Registers

TABLE 3. OUTPUT SELECT

S ₃	S ₂	S ₁	S ₀	Y ₇₋₀
0	0	0	0	A0
0	0	0	1	A1
0	0	1	0	A2
0	0	1	1	A3
0	1	0	0	A4
0	1	0	1	A5
0	1	1	0	A6
0	1	1	1	0 (L29C524) A7 (L29C525)
1	0	0	0	B0
1	0	0	1	B1
1	0	1	0	B2
1	0	1	1	B3
1	1	0	0	B4
1	1	0	1	B5
1	1	1	0	B6
1	1	1	1	D ₇₋₀ (L29C524) B ₇ (L29C525)

MAXIMUM RATINGS <i>Above which useful life may be impaired (Notes 1, 2, 3, 8)</i>	
Storage temperature	-65°C to +150°C
Operating ambient temperature	-55°C to +125°C
V _{CC} supply voltage with respect to ground	-0.5 V to +7.0 V
Input signal with respect to ground	-3.0 V to +7.0 V
Signal applied to high impedance output	-3.0 V to +7.0 V
Output current into low outputs	25 mA
Latchup current	> 400 mA

OPERATING CONDITIONS <i>To meet specified electrical and switching characteristics</i>		
Mode	Temperature Range (Ambient)	Supply Voltage
Active Operation, Commercial	0°C to +70°C	4.75 V ≤ V _{CC} ≤ 5.25 V
Active Operation, Military	-55°C to +125°C	4.50 V ≤ V _{CC} ≤ 5.50 V

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ELECTRICAL CHARACTERISTICS <i>Over Operating Conditions (Note 4)</i>						
Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
V _{OH}	Output High Voltage	V _{CC} = Min., I _{OH} = -12 mA	2.4			V
V _{OL}	Output Low Voltage	V _{CC} = Min., I _{OL} = 24 mA			0.5	V
V _{IH}	Input High Voltage		2.0		V _{CC}	V
V _{IL}	Input Low Voltage	(Note 3)	0.0		0.8	V
I _{IX}	Input Current	Ground ≤ V _{IN} ≤ V _{CC} (Note 12)			±20	µA
I _{OZ}	Output Leakage Current	Ground ≤ V _{OUT} ≤ V _{CC} (Note 12)			±20	µA
I _{CC1}	V _{CC} Current, Dynamic	(Notes 5, 6)		10	35	mA
I _{CC2}	V _{CC} Current, Quiescent	(Note 7)			1.0	mA

SWITCHING CHARACTERISTICS

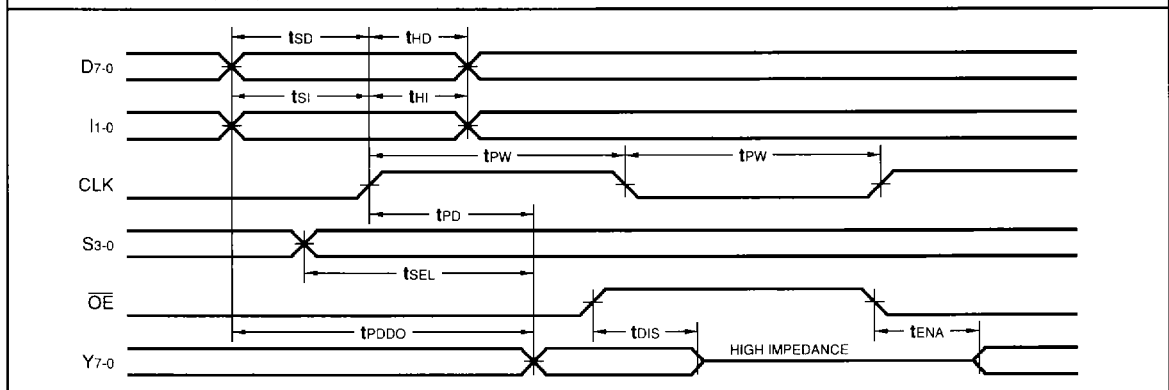
COMMERCIAL OPERATING RANGE (0°C to +70°C) Notes 9, 10 (ns)

Symbol	Parameter	L29C524/525-			
		20		15	
		Min	Max	Min	Max
t _{PD}	Clock to Output Delay		20		15
t _{SEL}	Select to Output Delay		20		15
t _{PDDO}	Data to Output Delay (L29C524)		20		15
t _{PW}	Clock Pulse Width	12		10	
t _{SD}	Data Setup Time	7		5	
t _{HD}	Data Hold Time	0		0	
t _{SI}	Instruction Setup Time	7		5	
t _{HI}	Instruction Hold Time	2		2	
t _{ENA}	Three-State Output Enable Delay (Note 11)		15		15
t _{DIS}	Three-State Output Disable Delay (Note 11)		13		13

MILITARY OPERATING RANGE (-55°C to +125°C) Notes 9, 10 (ns)

Symbol	Parameter	L29C524/525-			
		25		20	
		Min	Max	Min	Max
t _{PD}	Clock to Output Delay		25		20
t _{SEL}	Select to Output Delay		25		20
t _{PDDO}	Data to Output Delay (L29C524)		25		20
t _{PW}	Clock Pulse Width	12		12	
t _{SD}	Data Setup Time	7		7	
t _{HD}	Data Hold Time	2		2	
t _{SI}	Instruction Setup Time	7		7	
t _{HI}	Instruction Hold Time	2		2	
t _{ENA}	Three-State Output Enable Delay (Note 11)		15		15
t _{DIS}	Three-State Output Disable Delay (Note 11)		13		13

SWITCHING WAVEFORMS



NOTES

1. Maximum Ratings indicate stress specifications only. Functional operation of these products at values beyond those indicated in the Operating Conditions table is not implied. Exposure to maximum rating conditions for extended periods may affect reliability.
2. The products described by this specification include internal circuitry designed to protect the chip from damaging substrate injection currents and accumulations of static charge. Nevertheless, conventional precautions should be observed during storage, handling, and use of these circuits in order to avoid exposure to excessive electrical stress values.
3. This device provides hard clamping of transient undershoot and overshoot. Input levels below ground or above VCC will be clamped beginning at -0.6 V and VCC + 0.6 V. The device can withstand indefinite operation with inputs in the range of -0.5 V to +7.0 V. Device operation will not be adversely affected, however, input current levels will be well in excess of 100 mA.
4. Actual test conditions may vary from those designated but operation is guaranteed as specified.
5. Supply current for a given application can be accurately approximated by:

$$\frac{NCV^2F}{4}$$
 where
 N = total number of device outputs
 C = capacitive load per output
 V = supply voltage
 F = clock frequency
6. Tested with all outputs changing every cycle and no load, at a 5 MHz clock rate.
7. Tested with all inputs within 0.1 V of VCC or Ground, no load.
8. These parameters are guaranteed but not 100% tested.

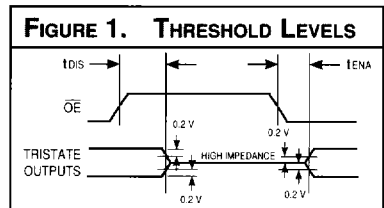
9. AC specifications are tested with input transition times less than 3 ns, output reference levels of 1.5 V (except tENA/tDIS test), and input levels of nominally 0 to 3.0 V. Output loading may be a resistive divider which provides for specified IOH and IOL at an output voltage of VOH min and VOL max respectively. Alternatively, a diode bridge with upper and lower current sources of IOH and IOL respectively, and a balancing voltage of 1.5 V may be used. Parasitic capacitance is 30 pF minimum, and may be distributed. For tENABLE and tDISABLE measurements, the load current is increased to 10 mA to reduce the RC delay component of the measurement.

This device has high-speed outputs capable of large instantaneous current pulses and fast turn-on/turn-off times. As a result, care must be exercised in the testing of this device. The following measures are recommended:

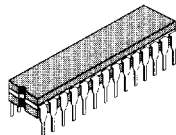
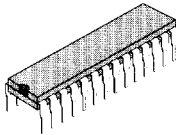
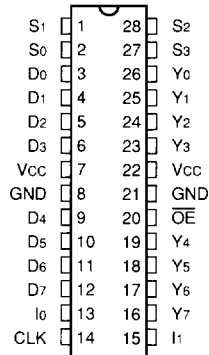
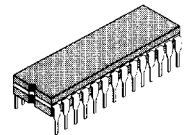
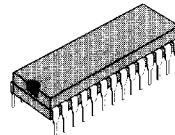
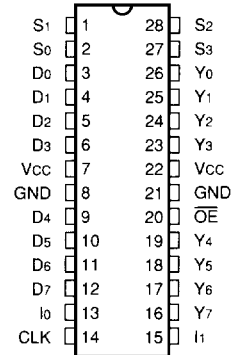
- a. A 0.1 µF ceramic capacitor should be installed between VCC and Ground leads as close to the Device Under Test (DUT) as possible. Similar capacitors should be installed between device VCC and the tester common, and device ground and tester common.
 - b. Ground and VCC supply planes must be brought directly to the DUT socket or contactor fingers.
 - c. Input voltages should be adjusted to compensate for inductive ground and VCC noise to maintain required DUT input levels relative to the DUT ground pin.
10. Each parameter is shown as a minimum or maximum value. Input requirements are specified from the point of view of the external system driving the chip. Setup time, for example, is specified as a minimum since the external system must supply at least that much time to meet the worst-case requirements of all parts. Responses from the internal circuitry are specified from

the point of view of the device. Output delay, for example, is specified as a maximum since worst-case operation of any device always provides data within that time.

11. Transition is measured ±200 mV from steady-state voltage with specified loading.
12. These parameters are only tested at the high temperature extreme, which is the worst case for leakage current.



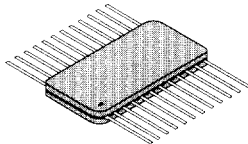
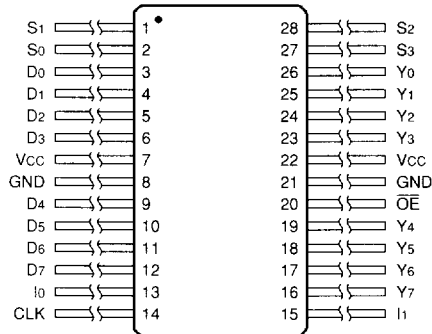
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L29C524 — ORDERING INFORMATION
28-pin — 0.3" wide

28-pin — 0.4" wide


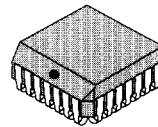
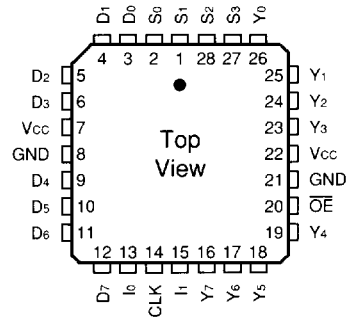
Speed	Plastic DIP (P10)	Ceramic DIP (C5)	Plastic DIP (P11)	Ceramic DIP (C10)
0°C to +70°C — COMMERCIAL SCREENING				
20 ns 15 ns	L29C524PC20 L29C524PC15	L29C524CC20 L29C524CC15	L29C524NC20 L29C524NC15	L29C524IC20 L29C524IC15
-55°C to +125°C — COMMERCIAL SCREENING				
25 ns 20 ns		L29C524CM25 L29C524CM20		L29C524IM25 L29C524IM20
-55°C to +125°C — MIL-STD-883 COMPLIANT				
25 ns 20 ns		L29C524CMB25 L29C524CMB20		L29C524IMB25 L29C524IMB20

L29C524 — ORDERING INFORMATION

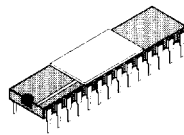
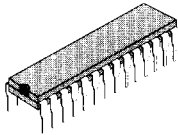
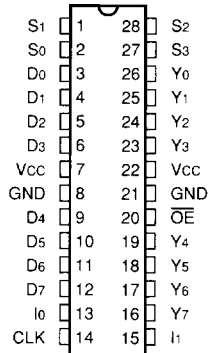
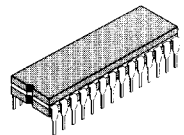
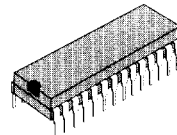
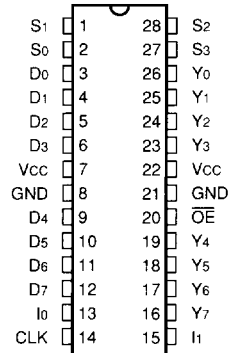
28-pin



28-pin



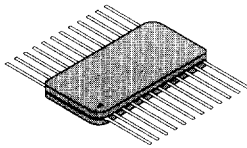
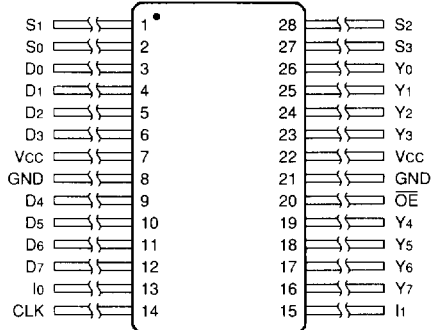
Speed	Ceramic Flatpack (M2)	Plastic J-Lead Chip Carrier (J4)
0°C to +70°C — COMMERCIAL SCREENING		
20 ns	L29C524MC20	L29C524JC20
15 ns	L29C524MC15	L29C524JC15
-55°C to +125°C — COMMERCIAL SCREENING		
25 ns	L29C524MM25	
20 ns	L29C524MM20	
-55°C to +125°C — MIL-STD-883 COMPLIANT		
25 ns	L29C524MMB25	
20 ns	L29C524MMB20	

L29C525 — ORDERING INFORMATION
28-pin — 0.3" wide

28-pin — 0.4" wide


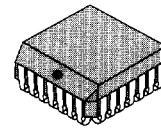
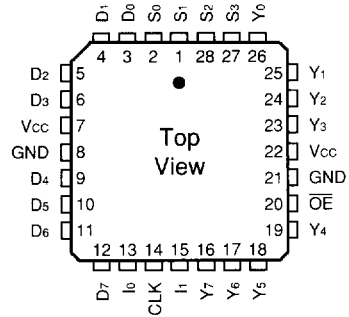
Speed	Plastic DIP (P10)	Sidebraze Hermetic DIP (D10)	Plastic DIP (P11)	Ceramic DIP (C10)
0°C to +70°C — COMMERCIAL SCREENING				
20 ns 15 ns	L29C525PC20 L29C525PC15	L29C525DC20 L29C525DC15	L29C525NC20 L29C525NC15	L29C525IC20 L29C525IC15
-55°C to +125°C — COMMERCIAL SCREENING				
25 ns 20 ns		L29C525DM25 L29C525DM20		L29C525IM25 L29C525IM20
-55°C to +125°C — MIL-STD-883 COMPLIANT				
25 ns 20 ns		L29C525DMB25 L29C525DMB20		L29C525IMB25 L29C525IMB20

L29C525 — ORDERING INFORMATION

28-pin



28-pin



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Speed	Ceramic Flatpack (M2)	Plastic J-Lead Chip Carrier (J4)
	0°C to +70°C — COMMERCIAL SCREENING	
20 ns 15 ns	L29C525MC20 L29C525MC15	L29C525JC20 L29C525JC15
	-55°C to +125°C — COMMERCIAL SCREENING	
25 ns 20 ns	L29C525MM25 L29C525MM20	
	-55°C to +125°C — MIL-STD-883 COMPLIANT	
25 ns 20 ns	L29C525MMB25 L29C525MMB20	

